

<b>L Numb r</b>	<b>Hits</b>	<b>S arch T xt</b>	<b>DB</b>	<b>Time stamp</b>
1	2	("6387734").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:05
2	2	("6350668").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:31
3	2	("6350633").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:33
4	3	("6329288").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:34
5	42	(US-6271056-\$ or US-6153448-\$ or US-6020629-\$ or US-5977641-\$ or US-6350668-\$ or US-6075290-\$ or US-6130480-\$ or US-6278192-\$ or US-6326701-\$ or US-5949142-\$ or US-5886415-\$ or US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.	USPAT; US-PGPUB	2002/07/22 13:39
6	0	("I5 and ((copper or silver) near paste)").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:40

7	1	((US-6271056-\$ r US-6153448-\$ r US-6020629-\$ r US-5977641-\$ or US-6350668-\$ r US-6075290-\$ r US-6130480-\$ or US-6278192-\$ r US-6326701-\$ r US-5949142-\$ r US-5886415-\$ or US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((copper or silver) near paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:42
8	2	((US-6271056-\$ or US-6153448-\$ or US-6020629-\$ or US-5977641-\$ or US-6350668-\$ or US-6075290-\$ or US-6130480-\$ or US-6278192-\$ or US-6326701-\$ or US-5949142-\$ or US-5886415-\$ or US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((copper or silver) near5 paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:48

9	4	((US-6271056-\$ or US-6153448-\$ r US-6020629-\$ or US-5977641-\$ or US-6350668-\$ r US-6075290-\$ r US-6130480-\$ or US-6278192-\$ or US-6326701-\$ r US-5949142-\$ r US-5886415-\$ or US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((conductive or conducting) near (resin or epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:49
10	11	((US-6271056-\$ or US-6153448-\$ or US-6020629-\$ or US-5977641-\$ or US-6350668-\$ or US-6075290-\$ or US-6130480-\$ or US-6278192-\$ or US-6326701-\$ or US-5949142-\$ or US-5886415-\$ or US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((conductive or conducting) near5 (resin or epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:51

11	14	((US-6271056-\$ r US-6153448-\$ r US-6020629-\$ or US-5977641-\$ or US-6350668-\$ or US-6075290-\$ or US-6130480-\$ r US-6278192-\$ or US-6326701-\$ or US-5949142-\$ or US-5886415-\$ r US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((conductive or conducting) near5 (resin or epoxy or paste))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 13:51
12	16	((US-6271056-\$ or US-6153448-\$ or US-6020629-\$ or US-5977641-\$ or US-6350668-\$ or US-6075290-\$ or US-6130480-\$ or US-6278192-\$ or US-6326701-\$ or US-5949142-\$ or US-5886415-\$ or US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((conductive or conducting) near5 (resin or epoxy or paste or solder))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 14:07

13	4	(((US-6271056-\$ r US-6153448-\$ or US-6020629-\$ r US-5977641-\$ or US-6350668-\$ r US-6075290-\$ or US-6130480-\$ r US-6278192-\$ or US-6326701-\$ r US-5949142-\$ or US-5886415-\$ r US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((conductive or conducting) near5 (resin or epoxy or paste or solder))) and (solder near resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 14:09
14	5	(((US-6271056-\$ or US-6153448-\$ or US-6020629-\$ or US-5977641-\$ or US-6350668-\$ or US-6075290-\$ or US-6130480-\$ or US-6278192-\$ or US-6326701-\$ or US-5949142-\$ or US-5886415-\$ or US-5889333-\$ or US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((conductive or conducting) near5 (resin or epoxy or paste or solder))) and (solder near5 resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 14:09

15	7	(((US-6271056-\$ or US-6153448-\$ or US-6020629-\$ or US-5977641-\$ r US-6350668-\$ or US-6075290-\$ r US-6130480-\$ or US-6278192-\$ r US-6326701-\$ or US-5949142-\$ or US-5886415-\$ r US-5889333-\$ r US-5892273-\$ or US-6355975-\$ or US-6365439-\$ or US-6355500-\$ or US-6342728-\$ or US-6307269-\$ or US-6353255-\$ or US-6342726-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6403460-\$ or US-6181569-\$).did. or (US-6350633-\$ or US-6107164-\$).did. or (US-20020056741-\$ or US-20020094601-\$ or US-20020005568-\$ or US-20020033530-\$ or US-20020050642-\$ or US-20020034872-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002724-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20020064935-\$ or US-20020001937-\$ or US-20020076911-\$).did.) and ((conductive or conducting) near5 (resin or epoxy or paste or solder))) and (photosensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 14:09
-	1	crack and warp and (csp or "chip scale package") and "wafer level"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:30
-	7	crack and warp and (csp or "chip scale package") and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:32
-	8	("5886415"   "5889333"   "5892273"   "5949142"   "6051450"   "6075290"   "6111309"   "6130480").PN.	USPAT	2002/07/19 11:31
-	424	tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:33
-	256	tsubosaki and kunihiro	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:33
-	0	kunihiro adj tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:33

-	256	kunihir near tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:33
-	0	kunihir adj2 tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:33
-	0	kunihiro adj10 tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:33
-	24	(kunihiro near tsubosaki) and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:36
-	0	temperature and crack and warp and substrate and yield and ((polish or polished or polishing) near (insulation or isolation or insulating or dielectric))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:38
-	1075	(polish or polishing or polished) near (insulating or isolation or insulation or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:39
-	0	((polish or polishing or polished) near (insulating or isolation or insulation or dielectric)) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:39
-	24	((polish or polishing or polished) near (insulating or isolation or insulation or dielectric)) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:40
-	1	((polish or polishing or polished) near (insulating or isolation or insulation or dielectric)) and electroless) and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:41
-	0	((polish or polishing or polished) near (insulating or isolation or insulation or dielectric)) and electroless) and ("chip scale package")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:41

-	191647	Electrode near10 (insulation or insulating or isolation or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:42
-	20447	Electrode near (insulation or insulating or isolation or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:44
-	63	(electrode near (insulation or insulating or isolation or dielectric)) and electroless and (polish or polishing or polished)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:44
-	1	((electrode near (insulation or insulating or isolation or dielectric)) and electroless and (polish or polishing or polished)) and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:44
-	144602	electrode near5 (insulation or insulating or isolation or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:44
-	259	(electrode near5 (insulation or insulating or isolation or dielectric)) and electroless and (polish or polishing or polished)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:44
-	9	((electrode near5 (insulation or insulating or isolation or dielectric)) and electroless and (polish or polishing or polished)) and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:46
-	0	((electrode near5 (insulation or insulating or isolation or dielectric)) and electroless and (polish or polishing or polished)) and kunihiro and tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:46
-	7	(electrode near5 (insulation or insulating or isolation or dielectric)) and kunihiro and tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:47
-	24	csp and kunihiro and tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:51



-	0	(( <b>"electr lytic plate" or "electr lytic plat d"</b> ) and csp) and el ctr l ss	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:52
-	5	( <b>"electr lytic plat " or "el ctrolytic plat d"</b> ) and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:52
-	123	( <b>"electrolytic plate" or "electrolytic plated"</b> ) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:52
-	0	(( <b>"electrolytic plate" or "electrolytic plated"</b> ) and electroless) and tsubosaki and kunihiro	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:53
-	64	<b>electrolytic and electroless and csp</b>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:54
-	64	( <b>electrolytic or electrolytically</b> ) and electroless and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:54
-	0	(( <b>electrolytic or electrolytically</b> ) and electroless and csp) and tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:54
-	16	(( <b>electrolytic or electrolytically</b> ) and electroless and csp) and crack	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:54
-	3	((( <b>electrolytic or electrolytically</b> ) and electroless and csp) and crack) and warp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:56
-	0	(( <b>electrolytic or electrolytically</b> ) and electroless and csp) and (csp.ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:56

-	1	((electrolytic or electrolytically) and electroless and csp) and (csp.clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:56
-	30	((electrolytic or electrolytically) and electroless and csp) and csp and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:57
-	29	((electrolytic or electrolytically) and electroless and csp) and csp and wafer) and (bump or solder or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 11:58
-	12	((electrolytic or electrolytically) and electroless and csp) and csp and wafer) and (bump or solder or ball)) and (polish or polished or polishing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:01
-	134	(csp or "chip size package" or "chip scale package") and (plate or plated or plating) and (polish or polished or polishing) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:03
-	0	((csp or "chip size package" or "chip scale package") and (plate or plated or plating) and (polish or polished or polishing) and wafer) and (electrolytic or electrolytically) and electroless) and tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:05
-	30	((csp or "chip size package" or "chip scale package") and (plate or plated or plating) and (polish or polished or polishing) and wafer) and (electrolytic or electrolytically) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:07
-	36	(US-6326701-\$ or US-6278192-\$ or US-6130480-\$ or US-6075290-\$ or US-5949142-\$ or US-5892273-\$ or US-5889333-\$ or US-5886415-\$ or US-6365439-\$ or US-6355975-\$ or US-6355500-\$ or US-6353255-\$ or US-6342728-\$ or US-6342726-\$ or US-6307269-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6350633-\$ or US-6181569-\$ or US-6107164-\$ or US-6350668-\$ or US-6153448-\$ or US-5977641-\$).did. or (US-20020034872-\$ or US-20020050642-\$ r US-20010040285-\$ or US-20010008304-\$ r US-20010002064-\$ or US-20010002069-\$ r US-20010002724-\$ r US-20020033530-\$ r US-20020001937-\$ r US-20020076911-\$ r US-20020064935-\$).did.	USPAT; US-PGPUB	2002/07/19 12:11

-	9	((US-6326701-\$ r US-6278192-\$ r US-6130480-\$ r US-6075290-\$ r US-5949142-\$ r US-5892273-\$ or US-5889333-\$ r US-5886415-\$ r US-6365439-\$ r US-6355975-\$ or US-6355500-\$ r US-6353255-\$ or US-6342728-\$ or US-6342726-\$ or US-6307269-\$ or US-6329288-\$ or US-6387734-\$ or US-6380574-\$ or US-6297544-\$ or US-6350633-\$ or US-6181569-\$ or US-6107164-\$ or US-6350668-\$ or US-6153448-\$ or US-5977641-\$).did. or (US-20020034872-\$ or US-20020050642-\$ or US-20010040285-\$ or US-20010008304-\$ or US-20010002064-\$ or US-20010002069-\$ or US-20010002724-\$ or US-20020033530-\$ or US-20020001937-\$ or US-20020076911-\$ or US-20020064935-\$).did.) and wafer and (polish or polished or polishing) and (isolation or insulating or dielectric or passivation) and electroless and (plating or plate or plated) and (electrolytic or electrolytically) and (etch or etched or etching) and (bump or solder or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:19
-	111	wafer and (polish or polished or polishing) and (isolation or insulating or dielectric or passivation) and electroless and (plating or plate or plated) and (electrolytic or electrolytically) and (etch or etched or etching) and (bump or solder or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:15
-	0	((wafer and (polish or polished or polishing) and (isolation or insulating or dielectric or passivation) and electroless and (plating or plate or plated) and (electrolytic or electrolytically) and (etch or etched or etching) and (bump or solder or ball) ) and (csp or "chip scale package" or "chip size package")) and tsubosaki	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:16
-	29	(wafer and (polish or polished or polishing) and (isolation or insulating or dielectric or passivation) and electroless and (plating or plate or plated) and (electrolytic or electrolytically) and (etch or etched or etching) and (bump or solder or ball) ) and (csp or "chip scale package" or "chip size package")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:17

-	15	wafer and (polish or polished or polishing) and (isolation or insulating or dielectric or passivation) and electroless and (plating or plate or plated) and (electrolytic or electrolytically) and (etch or etched or etching) and (bump or solder or ball) and (csp or "chip scale package" or "chip size package") and (cure or curing or cured)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:20
-	4	wafer and (polish or polished or polishing) and (isolation or insulating or dielectric or passivation) and electroless and (plating or plate or plated) and (electrolytic or electrolytically) and (etch or etched or etching) and (bump or solder or ball) and (csp or "chip scale package" or "chip size package") and (cure or curing or cured) and ((conductive or conducting) near10 paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:21
-	2	wafer and (polish or polished or polishing) and (isolation or insulating or dielectric or passivation) and electroless and (plating or plate or plated) and (electrolytic or electrolytically) and (etch or etched or etching) and (bump or solder or ball) and (csp or "chip scale package" or "chip size package") and (cure or curing or cured) and ((conductive or conducting) near10 paste) and (sputter or sputtering or sputtered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:34
-	1	((polishing near (insulation or insulating or isolation or dielectric or passivation)) and (electroless adj (plate or plated or plating)) and ((electrolytic or electrolytically) adj (plate or plated or plating)) and (etch or etching or etched))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:38
-	1	((polishing near (insulation or insulating or isolation or dielectric or passivation)) and (electroless near (plate or plated or plating)) and ((electrolytic or electrolytically) near (plate or plated or plating)) and (etch or etching or etched))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:39
-	5864	(polishing near (insulation or insulating or isolation or dielectric or passivation)) electroless and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:40
-	5	(polishing near (insulation or insulating or isolation or dielectric or passivation)) and electroless and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:41
-	41	(polishing near5 (insulation or isolation or dielectric or passivation)) and electroless and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:42

-	1	((p lishing near5 (insulati n r insulating or is lati n or di l ctric r passivati n)) and el ctr less and electr lytic) and csp	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:44
-	10809	(insulation or insulating or di l ctric or isolation) near10 (polish or polished or polishing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:44
-	90	((insulation or insulating or dielectric or isolation) near10 (polish or polished or polishing)) and electroless and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:44
-	68	((((insulation or insulating or dielectric or isolation) near10 (polish or polished or polishing)) and electroless and electrolytic) and (sputter or sputtering or sputtered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:45
-	67	(((((insulation or insulating or dielectric or isolation) near10 (polish or polished or polishing)) and electroless and electrolytic) and (sputter or sputtering or sputtered)) and (etch or etched or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:48
-	41	(((((insulation or insulating or dielectric or isolation) near10 (polish or polished or polishing)) and electroless and electrolytic) and (sputter or sputtering or sputtered)) and (etch or etched or etching)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:45
-	2	(((((insulation or insulating or dielectric or isolation) near10 (polish or polished or polishing)) and electroless and electrolytic) and (sputter or sputtering or sputtered)) and (etch or etched or etching)) and wafer) and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:47
-	1	(((((insulation or insulating or dielectric or isolation) near10 (polish or polished or polishing)) and electroless and electrolytic) and (sputter or sputtering or sputtered)) and (etch or etched or etching)) and wafer) and ("chip size" or "chip scale")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:47
-	3895	(((((insulation or insulating or dielectric or isolation) near10 (polish or polished or polishing)) and electroless and electrolytic) and (sputter or sputtering or sputtered)) and (etch or etched or etching)) csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:48
-	2	(((((insulation or insulating or dielectric or is lati n) n ar10 (p lish or polish d r p lishing)) and electroless and l ctrolytic) and (sputter r sputtering or sputt r d)) and (etch r etch d or tching)) and csp	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:48

-	110	electrode and (insulation or insulating or dielectric or passivation) and (wiring or metal or interconnect or wire or interconnection) and bump and paste and (cure or cure or curing) and (conductive or conducting or conduct) and solder and resist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:52
-	76	electrode and (insulation or insulating or dielectric or passivation) and (wiring or metal or interconnect or wire or interconnection) and bump and paste and (cure or cure or curing) and (conductive or conducting or conduct) and solder and resist and ball and (plate or plating or plated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:53
-	63	electrode and (insulation or insulating or dielectric or passivation) and (wiring or metal or interconnect or wire or interconnection) and bump and paste and (cure or cure or curing) and (conductive or conducting or conduct) and solder and resist and ball and (plate or plating or plated) and (etch or etched or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:53
-	33	electrode and (insulation or insulating or dielectric or passivation) and (wiring or metal or interconnect or wire or interconnection) and bump and paste and (cure or cure or curing) and (conductive or conducting or conduct) and solder and resist and ball and (plate or plating or plated) and (etch or etched or etching) and (sputter or sputtering or sputtered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:54
-	24	electrode and (insulation or insulating or dielectric or passivation) and (wiring or metal or interconnect or wire or interconnection) and bump and paste and (cure or cure or curing) and (conductive or conducting or conduct) and solder and resist and ball and (plate or plating or plated) and (etch or etched or etching) and (sputter or sputtering or sputtered) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:54
-	6	electrode and (insulation or insulating or dielectric or passivation) and (wiring or metal or interconnect or wire or interconnection) and bump and paste and (cure or cure or curing) and (conductive or conducting or conduct) and solder and resist and ball and (plate or plating or plated) and (etch or etched or etching) and (sputter or sputtering or sputtered) and wafer and csp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 12:58

-	7	el ctr de and (insulati n r insulating r di lectri r passivati n) and (wiring or metal r interc nn ct r wire or int rconnection) and past and (cur r cure r curing) and (c nductive r conducting r c nduct) and (plate or plating or plat d) and (etch or etched or etching) and (sputter or sputtering or sputtered) and wafer and csp and (solder or ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:04
-	49	wafer and csp and ((wiring or wire or interconnection or interconnect) adj layer) and ((insulating or insulation or dielectric or passivation) adj layer) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:07
-	26	(wafer and csp and ((wiring or wire or interconnection or interconnect) adj layer) and ((insulating or insulation or dielectric or passivation) adj layer) and electrode) and (solder or ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:07
-	10	wafer and csp and ((wiring or wire or interconnection or interconnect) adj layer) and ((insulating or insulation or dielectric or passivation) adj layer) and electrode and (solder or ball or bump) and (plate or plated or plating) and (polish or polished or polishing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:12
-	22	electrolytic and electroless and (plated or plating or plate) and (polish or polished or polishing) and (sputter or sputtering or sputtered) and (etch or etched or etching) and solder and (insulation or insulating or dielectric or isolation) and (csp or "chip scale package" or "chip size package") and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:20
-	2	electrolytic and electroless and (plated or plating or plate) and (polish or polished or polishing) and (sputter or sputtering or sputtered) and (etch or etched or etching) and solder and (insulation or insulating or dielectric or isolation) and ((csp or "chip scale package" or "chip size package").clm.) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:23
-	145	((csp or "chip scale package" or "chip size package").clm.) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:33
-	4	(((((csp or "chip scale package" or "chip size package").clm.) and waf r) and l ctr l ss and l ctr lytic) and (p lish r polish d r p lishing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:26

-	17	(((csp or "chip scale package" or "chip size package").clm.) and wafer) and electroless and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:27
-	69	(((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:41
-	19	(((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer and ((csp or "chip scale package" or "chip size package").ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:38
-	7	(((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer and ((csp or "chip scale package" or "chip size package").ti.)) and (polish or polished or polishing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:40
-	0	((((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer and ((csp or "chip scale package" or "chip size package").ti.)) and (polish or polished or polishing)) and electroless) and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:39
-	3	((((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer and ((csp or "chip scale package" or "chip size package").ti.)) and (polish or polished or polishing)) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:39
-	5	(((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer and ((csp or "chip scale package" or "chip size package").ti.)) and (polish or polished or polishing) and plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:40
-	5	((((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer) and (polish or polished or polishing) and (plate or plating or plated)) and (etch or etched or etching)) and (sputter or sputtering or sputtered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:42
-	7	(((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer) and (polish or polished or polishing) and (plate or plating or plated)) and (etch or etched or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:43
-	11	(((csp or "chip scale package" or "chip size package") and wafer).clm.) and wafer) and (polish or polished or polishing) and (plate or plating or plated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:45



-	0	(202/0056741).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:45
-	0	(2002/0056741).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:45
-	0	(2002/0056741 A1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:45
-	0	(US 2002/0056741 A1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:46
-	28	"0056741"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:47
-	0	2002/0056741	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:48
-	1	09/834,629	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:48
-	0	09794,108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:49
-	1	09/794,108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:49
-	1	09/738,667	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:49

-	1	("6403460").PN.	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:49
-	2	("5977641").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:49
-	2	("6350633").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:50
-	2	("6387734").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:50
-	1	10/052,143	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:50
-	3	("6,329,288").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:50
-	2	("6,350,668").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:51
-	2	("6,181,569").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:51
-	0	("97 98 99 100 101 102 103 04 105 106 107 108").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:52
-	440	09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) tsub saki 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:52

-	18	09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) (("5977641").PN.) ("6350633").PN.) (("6387734").PN.) 10/052,143 (("6,329,288").PN.) ("6,350,668").PN.) (("6,181,569").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:52
-	8	(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) (("5977641").PN.) ("6350633").PN.) (("6387734").PN.) 10/052,143 (("6,329,288").PN.) ("6,350,668").PN.) (("6,181,569").PN.)) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:53
-	8	((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) (("5977641").PN.) ("6350633").PN.) (("6387734").PN.) 10/052,143 (("6,329,288").PN.) ("6,350,668").PN.) (("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:54
-	5	((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) (("5977641").PN.) ("6350633").PN.) (("6387734").PN.) 10/052,143 (("6,329,288").PN.) ("6,350,668").PN.) (("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:54
-	5	(((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) (("5977641").PN.) ("6350633").PN.) (("6387734").PN.) 10/052,143 (("6,329,288").PN.) ("6,350,668").PN.) (("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:55
-	2	(((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) (("5977641").PN.) ("6350633").PN.) (("6387734").PN.) 10/052,143 (("6,329,288").PN.) ("6,350,668").PN.) (("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:56

-	2	((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and lectr d ) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:56
-	2	((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)) and (polish or polished or polishing or grind or grinding or grinded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:56
-	2	((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)) and (polish or polished or polishing or grind or grinding or grinded)) and (etch or etched or etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:57
-	2	((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)) and (polish or polished or polishing or grind or grinding or grinded)) and (etch or etched or etching)) and (sputter or sputtered or sputtering)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 13:57

-	0	<p>((((((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and l ctr d ) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)) and (polish or polished or polishing or grind or grinding or grinded)) and (etch or etched or etching)) and (sputter or sputtered or sputtering)) and paste</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 13:58</p>
-	124	<p>((polish or polishing or polished) near (insulating or isolation or insulation or dielectric)) and resin</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 13:58</p>
-	2	<p>((((((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)) and (polish or polished or polishing or grind or grinding or grinded)) and (etch or etched or etching)) and (sputter or sputtered or sputtering)) and (resin or epoxy or paste)</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 13:58</p>
-	2	<p>((((((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and electrode) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)) and (polish or polished or polishing or grind or grinding or grinded)) and (etch or etched or etching)) and (sputter or sputtered or sputtering)) and (resin or epoxy or paste)) and ((cure or cured or curing) near10 (epoxy or resin or paste))</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 13:59</p>

-	0	<p>((((((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and electr de) and (wiring or metal or interconnect or interconnection or wire)) and bump) and solder) and (cure or cured or curing)) and (plate or plating or plated)) and (polish or polished or polishing or grind or grinding or grinded)) and (etch or etched or etching)) and (sputter or sputtered or sputtering)) and (resin or epoxy or paste)) and ((cure or cured or curing) near10 (epoxy or resin or paste) near10 (conducting or conductive or conduct))</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 14:01</p>
-	8	<p>(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and (polishing or polished or polish or grinding or grinded or grind) and (plate or plating or plated) and (etch or etched or etching) and (solder or bump or ball) and (sputter or sputtered or sputtering)</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 14:09</p>
-	7	<p>((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and (polishing or polished or polish or grinding or grinded or grind) and (plate or plating or plated) and (etch or etched or etching) and (solder or bump or ball) and (sputter or sputtered or sputtering) ) and electroless</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 14:04</p>
-	7	<p>((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and (polishing or polished or polish or grinding or grinded or grind) and (plate or plating or plated) and (etch or etched or etching) and (solder or bump r ball) and (sputt r r sputter d r sputtering) ) and el ctr less) and el ctr lytic</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2002/07/19 14:04</p>

-	7	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and (p lishing r polished or polish or grinding or grinded or grind) and (plate or plating or plated) and (etch or etched or etching) and (solder or bump or ball) and (sputter or sputtered or sputtering) ) and electroless) and electrolytic) and ("wiring layer" or "wire layer" or "metal layer" or interconnect or interconnection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:06
-	1	((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and (polishing or polished or polish or grinding or grinded or grind) and (plate or plating or plated) and (etch or etched or etching) and (solder or bump or ball) and (sputter or sputtered or sputtering) ) and electroless) and electrolytic) and ("wiring layer" or "wire layer" or "metal layer" or interconnect or interconnection)) and ((conductive or conducting or conduct) near10 (paste or epoxy or resin))) and (solder near10 resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:07
-	5	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and (polishing or polished or polish or grinding or grinded or grind) and (plate or plating or plated) and (etch or etched or etching) and (solder or bump or ball) and (sputter or sputtered or sputtering) ) and electroless) and electrolytic) and ("wiring layer" or "wire layer" or "metal layer" or interconnect or interconnection)) and ((conductive or conducting or conduct) near10 (paste or epoxy or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:07
-	1	(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and "s lder resist"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:10

-	0	(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.) and ((conducting r conductive) adj (paste or epoxy or resin))	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:10
-	0	(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.) and ((conducting or conductive) near (paste or epoxy or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:11
-	13	(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.) and (paste or epoxy or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:11
-	7	((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.) and (paste or epoxy or resin)) and (cure or cured or curing)) and (bump or ball or solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:11
-	8	((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.) and (paste or epoxy or resin)) and (cure or cured or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:13
-	11	(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.) and ((insulating or isolation or dielectric or passivation) adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:19
-	10	((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.) and ((insulating r isolati n or dielectric r passivati n) adj lay r)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:19



-	3	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating or isolation or dielectric or passivation) adj layer)) and wafer) and electrode	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:15
-	3	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating or isolation or dielectric or passivation) adj layer)) and wafer) and electrode) and (polishing or polish or polished or grind or grinding or grinded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:15
-	3	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating or isolation or dielectric or passivation) adj layer)) and wafer) and electrode) and (polishing or polish or polished or grind or grinding or grinded)) and electroless and (plate or plated or plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:16
-	3	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating or isolation or dielectric or passivation) adj layer)) and wafer) and electrode) and (polishing or polish or polished or grind or grinding or grinded)) and electroless and (plate or plated or plating)) and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:16
-	3	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating or isolation or dielectric or passivation) adj layer)) and wafer) and electrode) and (p lishing or p lish r p lish d r grind r grinding or grinded)) and l ctroless and (plat r plated r plating)) and l ctr lytic) and (etch r etching r tched)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:16

-	3	((((((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating r isolation or dielectric or passivation) adj layer)) and wafer) and electrode) and (polishing or polish or polished or grind or grinding or grinded)) and electroless and (plate or plated or plating)) and electrolytic and (etch or etching or etched)) and (solder or ball or bump)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:17
-	8	(09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:18
-	12	(((electrolytic or electrolytically) and electroless and csp) and csp and wafer) and (bump or solder or ball)) and (polish or polished or polishing) and (plate or plated or plating) and electroless and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:20
-	7	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating or isolation or dielectric or passivation) adj layer)) and wafer) and (polish or polished or polishing) and (plate or plated or plating) and electroless and electrolytic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:20
-	6	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating or isolation or dielectric or passivation) adj layer)) and wafer) and (polish or polished or polishing) and (plate or plated or plating) and electroless and electrolytic and (etch or etched or etching) and (solder or ball or bump) and (sputter or sputtering or sputtered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:21

-	7	(((09/834,629 09794,108 09/794,108 09/738,667 ("6403460").PN.) ("5977641").PN.) ("6350633").PN.) ("6387734").PN.) 10/052,143 ("6,329,288").PN.) ("6,350,668").PN.) ("6,181,569").PN.)) and ((insulating r isolation or dielectric or passivation) adj layer)) and wafer) and (polish or polished or polishing) and (plate or plated or plating) and electroless and electrolytic and (etch or etched or etching) and (solder or ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/19 14:22
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